



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-12-04
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HJO7*L264EA6	A	BO2A	2017-12-04
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package: O7 SO 08 .15 JEDEC; MDF valid for UC2843BD1013TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	H107*L264EA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.181	mg	supplier	die	Silicon (Si)	7440-21-3		3.088	mg	970764	38600
				supplier	metallization	Aluminium (Al)	7429-90-5		0.038	mg	11946	475
				supplier	Passivation	Silicon Nitride	12033-89-5		0.013	mg	4087	163
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	5973	238
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	629	25
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.021	mg	6602	263
Leadframe	Copper & its alloys	30.328	mg	supplier	alloy	Copper (Cu)	7440-50-8		30.072	mg	991559	375900
				supplier	alloy	Iron (Fe)	7439-89-6		0.015	mg	495	188
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.024	mg	791	300
				supplier	metallization	Silver (Ag)	7440-22-4		0.217	mg	7155	2713
Die attach	Other Organic Materials	1.114	mg	supplier	glue	Silver (Ag)	7440-22-4		0.980	mg	879713	12250
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.056	mg	50269	700
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.056	mg	50269	700
				supplier	glue	Acrylate polymer	87320-05-6		0.022	mg	19749	275
Bonding wires	Other inorganic materials	0.082	mg	supplier	wire	Copper (Cu)	7440-50-8		0.082	mg	1000000	1025
Encapsulation	Other Organic Materials	44.237	mg	supplier	mold compound	Silica, vitreous	60676-86-0		38.309	mg	865995	478863
				supplier	mold compound	Epoxy Resin	Proprietary		3.318	mg	75005	41475
				supplier	mold compound	Phenol Resin	Proprietary		2.212	mg	50003	27650
				supplier	mold compound	Carbon black	1333-86-4		0.221	mg	4996	2763
connections coating	Solder	1.058	mg	supplier	mold compound	Bismuth compound	7440-69-9		0.177	mg	4001	2213
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.058	mg	1000000	13225